

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows.

Claims 1 - 7 (cancelled)

8. (currently amended) A lead-free solder paste comprising a first solder alloy powder of a first solder alloy, a second solder alloy powder of a second solder alloy, and a flux mixed with the first and second solder alloy powders, wherein the main peak temperature of the first solder alloy measured by differential thermal analysis is and the second solder alloy have a difference of at least 10°C in their lower than the main peak temperature of the second solder alloy measured by differential thermal analysis, the first solder alloy has a composition consisting of 3 - 4 mass % of Ag, 6 - 20 mass % of In, 0 - 1 mass % of Bi, and a balance of Sn, the second solder alloy has a composition consisting of 3 - 4 mass % of Ag, 0 - 1 mass % of Cu, 0 - 1 mass % of Bi, and a balance of Sn, and the overall composition after melting of the first and second solder alloy powders is consists of 3 - 4 mass % of Ag, 3 - 10 mass % of In, 0 - 1 mass % of Bi, 0 - 1 mass % of Cu, and a balance of Sn, and the first solder alloy contains 6 - 20 mass % of In.

9. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy is a Sn-Ag-In alloy and

the second solder alloy is a Sn-Ag alloy.

Claims 10 - 12 (cancelled)

13. (previously presented) A solder paste as claimed in claim 8 wherein:

the first solder alloy is selected from a Sn-Ag-In alloy and a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag-Cu alloy and a Sn-Ag-Bi-Cu alloy.

Claims 14 - 15 (cancelled)

16. (previously presented) A solder paste as claimed in claim 8 wherein the overall composition after melting of the first and second solder alloy powders contains 6 - 10 mass % of In.

17. (previously presented) A solder paste as claimed in claim 8 wherein the difference in the main peak temperatures of the first and second solder alloys is at least 20 °C.

Claim 18 (cancelled)

19. (currently amended) A solder paste as claimed in claim 8 wherein the first solder alloy is a Sn-Ag-In-Bi alloy.

20. (currently amended) A solder paste as claimed in claim 8 wherein the first solder alloy contains 12 - 20 mass % of In.

21. (currently amended) A solder paste as claimed in claim 8 wherein the second solder alloy contains greater than 0 and at most 1 mass % of Bi.

22. (currently amended) A solder paste as claimed in claim 8 wherein each of the first and second solder alloys contains greater than 0 and at most 1 mass % of Bi.

Claim 23 (cancelled)